

# (19) United States

## (12) Patent Application Publication (10) Pub. No.: US 2024/0215159 A1 Lee et al.

Jun. 27, 2024 (43) Pub. Date:

### (54) CIRCUIT BOARD AND MANUFACTURING METHOD THEREOF

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(21) Appl. No.: 18/131,019

(22)Filed: Apr. 5, 2023

(30)Foreign Application Priority Data

Dec. 26, 2022 (KR) ..... 10-2022-0184350

#### **Publication Classification**

(51) Int. Cl. H05K 1/03 (2006.01)H05K 1/11 (2006.01)H05K 3/00 (2006.01)H05K 3/10 (2006.01)

(52)U.S. Cl.

> CPC ..... H05K 1/0353 (2013.01); H05K 1/111 (2013.01); H05K 1/115 (2013.01); H05K 3/0017 (2013.01); H05K 3/103 (2013.01); H05K 2201/0939 (2013.01); H05K 2201/099 (2013.01)

#### (57) ABSTRACT

A circuit board according to an embodiment includes: a first insulating layer that does not include a reinforcing material; a conductive pad that protrudes above a surface of the first insulating layer, and a second insulating layer that is disposed below the first insulating layer and includes a reinforcing material. A corner of the conductive pad has a curved shape.

